| | |
|---|---|
| Session Title: | [TB3] Process and Equipment |
| Session Date: | November 21 (Tue.), 2023 |
| Session Time: | 14:25-15:55 |
| Session Room: | Room B (Grand Ballroom 1, 2F) |
| Session Chair: | Prof. Jihwan An (POSTECH, Korea) |

[TB3-1] [Invited] 14:25-14:55

Glass Wafer for Supporting Semiconductors

Masahiro Kobayashi, Yuici Suguro, and Tetsuya Kojima (Nippon Electric Glass Co., Ltd., Japan)

[TB3-2] [Invited] 14:55-15:15

Development of Heterogenous and Multi-Stack Flexible Packaging with Photo-Patternable Polymer Elastic Bumps

Hyunkyu Moon, Ah-Young Park, Seungman Kim, Seongheum Han, Jun-Yeob Song, and Jae Hak Lee (KIMM, Korea)

[TB3-3] [Invited] 15:15-15:35

Development Trends of Plasma System and Applications in Semiconductor Packaging and Substrate

Nam Son Park, Sung Yong Kim, Tae-Young Lee, Kyoung Min Kim (Tech Univ. of Korea, Korea), and Tae il Baek (Jesagi Hankook Co., Ltd., Korea)

[TB3-4] [Invited] 15:35-15:55

Adhesion of Plated Thick Film Metal on Epoxy Molding Compound under Thermal Cycle

Jae-Seong Jeong (KETI, Korea)